

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SATOSHI UNO	01/21/2013
HIDEAKI TSUCHIYA	01/21/2013
SHINJI YOKOGAWA	01/21/2013
RECEIVING PARTY DATA	
Name:	RENESAS ELECTRONICS CORPORATION
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Internal Address:	KAWASAKI-SHI
City:	KANAGAWA
State/Country:	JAPAN
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13781496
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NAME OF SUBMITTER:	STEPHEN A. BECKER
SIGNATURE:	/STEPHEN A. BECKER/
DATE SIGNED:	04/14/2014
Total Attachments: 1	
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(SAB)

Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Satoshi UNO (4) _____
(2) Hideaki TSUCHIYA (5) _____
(3) Shinji YOKOGAWA (6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

RENESAS ELECTRONICS CORPORATION

1753, Shimonumabe, Nakahara-ku, Kawasaki-shi,
Kanagawa 211-8668, Japan

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE

- (a) for which an application for United States Letters Patent was filed on _____,
and identified by United States Serial No. _____; or
- (b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) <u>Satoshi UNO</u> Name: Satoshi UNO	<u>January 21, 2013</u>
2) <u>Hideaki Tsuchiya</u> Name: Hideaki TSUCHIYA	<u>January 21, 2013</u>
3) <u>Shinji Yokogawa</u> Name: Shinji YOKOGAWA	<u>January 21, 2013</u>

PATENT

RECORDED: 04/14/2014

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